7. (Twice Amended)

A thin film resistor comprising:

a substrate;

a metal thin film resistive layer attached to the substrate, the metal thin film layer being non-tantalum;

a resistor termination attached on each end of the metal thin film resistive layer; and

an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the metal thin film resistive layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

13. (Twice Amended)

A nickel-chromium alloy thin film resistor comprising:

a substrate;

a nickel- chromium alloy thin film layer attached to the substrate;

a termination attached on each end of the nickel-chromium alloy thin film; and

an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the nickel-chromium alloy thin film layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

15. (Amended)

A nickel- chromium alloy thin film resistor comprising:

a substrate;

a nickel-chromium alloy thin film layer attached to the substrate;

a passivation layer directly overlaying and attaching to the nickel-chromium alloy layer; and

an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the passivation layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

Please add new claim 16 as follows:

16. A thin film resistor comprising:

a resistor substrate;

a metal thin film resistive layer attached to the substrate, the metal thin film layer being non-tantalum;

a resistor termination attached on each end of the metal thin film resistive layer;

a passivation layer directly overlaying the metal thin film resistive layer;

an outer moisture barrier consisting of tantalum pentoxide directly overlaying the passivation layer for reducing failures due to electrolytic corrosion under powered moisture conditions.